

具有电池短路和其他短路保护功能的 TPD3S714-Q1 汽车 USB 2.0 接口保护器件

1 项目符号

- 符合 AEC-Q100 标准 (1 级)
 - 工作温度范围: -40°C 至 $+125^{\circ}\text{C}$
- 提供功能安全
 - 可帮助进行功能安全系统设计的文档
- $V_{\text{BUS_CON}}$ 引脚上具有电池短路保护 (高达 18V) 和接地短路保护
- VD+ 和 VD- 引脚上具有电池短路保护 (高达 18V) 和 V_{BUS} 短路保护
- 在 $V_{\text{BUS_CON}}$ 、 VD+ 和 VD- 上提供 IEC 61000-4-2 ESD 保护
 - $\pm 8\text{kV}$ 接触放电
 - $\pm 15\text{kV}$ 气隙放电
- $V_{\text{BUS_CON}}$ 、 VD+ 和 VD- 引脚上具有 ISO 10605 330pF、330 Ω ESD 保护
 - $\pm 8\text{kV}$ 接触放电
 - $\pm 15\text{kV}$ 气隙放电
- 低 R_{ON} nFET V_{BUS} 开关 (典型值为 63m Ω)
- 高速数据开关 (-3dB 时的带宽为 1GHz)
- 断续电流限制
 - 550mA 过流限制 (最小值)
- 快速过压响应时间
 - 2 μs 典型值 (V_{BUS} 开关)
 - 200ns 典型值 (数据开关)
- 集成输入使能, 适用于 V_{BUS} 、 VD+ 和 VD-
- 故障输出信号
- 热关断特性
- 16 引脚 SSOP 封装 (4.9mm $\times$ 3.9mm)

2 应用

- 终端设备
 - 音响主机
 - 后座娱乐系统
 - 远程信息处理
 - USB 集线器
 - 导航模块
 - 媒体接口
- 接口
 - USB 2.0

3 说明

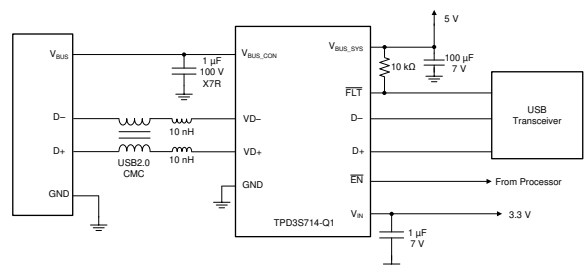
TPD3S714-Q1 是一款单芯片解决方案, 可为汽车 USB 集线器、音响主机、后座娱乐系统、远程信息处理和媒体接口应用中 USB 连接器的 V_{BUS} 和数据线路提供电池短路保护、短路保护以及 ESD 保护。集成的数据开关提供了出色的带宽, 能够在 USB 发生电池短路时更大限度地减少信号衰减。高达 1GHz 的带宽可利用汽车 USB 环境中常见的长系留线缆来实现干净的 USB 2.0 高速 (480Mbps) 眼图。

电池短路保护可隔离内部系统电路, 防止其受到 $V_{\text{BUS_CON}}$ 、 VD+ 和 VD- 引脚上任何过压情况的影响。在这些引脚上, TPD3S714-Q1 能够针对热插拔和直流事件处理高达 18V 的过压情况。过压保护电路可提供业界最可靠的电池短路隔离, 能够关闭开关并保护上游收发器免受有害电压和电流尖峰的影响。 $V_{\text{BUS_CON}}$ 引脚还提供了一个最高限值为 0.5A 的精确限流负载开关。过流保护会自动限制电流, 以便在发生接地短路时防止上游电源轨发生压降。此外, 该器件还在 $V_{\text{BUS_CON}}$ 、 VD+ 和 VD- 引脚上集成了系统级 IEC 61000-4-2 和 ISO 10605 ESD 保护功能, 无需使用高电压、低容值的外部 ESD 二极管

器件信息 (1)

器件型号	封装	封装尺寸 (标称值)
TPD3S714-Q1	SSOP (16)	4.90mm $\times$ 3.90mm

(1) 如需了解所有可用封装, 请参阅数据表末尾的可订购产品附录。



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典型应用原理图



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4 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision B (August 2017) to Revision C (August 2020)	Page
• 更新了整个文档的表、图和交叉参考的编号格式.....	1
• 向 特性 部分添加了功能安全链接.....	1

Changes from Revision A (April 2016) to Revision B (August 2017)	Page
• Updated ESD Protection on V_{BUS_CON}, VD+, VD- section.....	15

Changes from Revision * (January 2016) to Revision A (April 2016)	Page
• 更新了 典型应用原理图 、 图 7-1 和 图 7-2	1
• 更新了{4}{5}电气特性{6}{7} 表.....	1
• 向 电池短路容差 添加了内容.....	1
• 更新了 典型特性 中具有更准确数据的 IEC 波形图.....	1

5 Pin Configuration and Functions

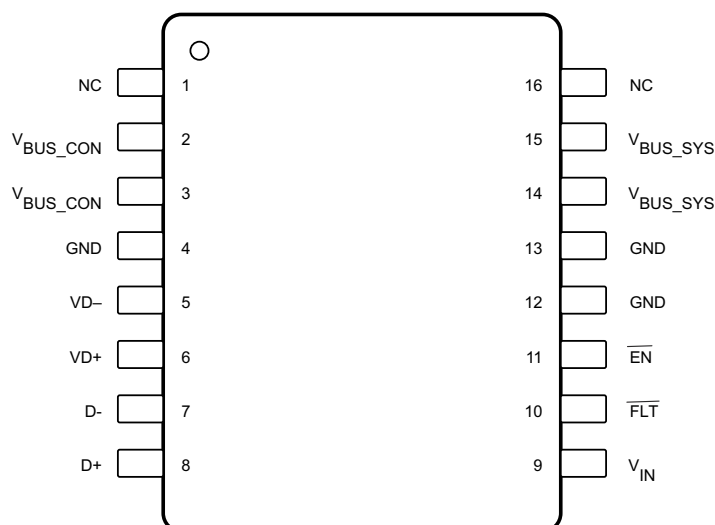


图 5-1. DBQ Package 16-Pin SSOP Top View

Pin Functions

PIN		TYPE	DESCRIPTION
NO.	NAME		
1	NC	NC	No connect, leave floating or connect to ground. Do not connect to V _{BUS_CON}
2	V _{BUS_CON}	O	Connect to USB connector V _{BUS_CON} ; provides IEC 61000-4-2 ESD protection
3			
4	GND	Ground	Connect to PCB ground plane
5	VD -	I/O	Connect to USB connector D - ; provides IEC 61000-4-2 ESD protection
6	VD+	I/O	Connect to USB connector D+; provides IEC 61000-4-2 ESD protection
7	D -	I/O	Connect to internal D - transceiver
8	VD+	I/O	Connect to internal D+ transceiver
9	V _{IN}	I	Connect to 3.3-V I/O. Controls the OVP threshold for VD+/VD -
10	FLT	O	Open-Drain fault pin. Refer device description for operation
11	EN	I	Enable Active-Low Input. Drive EN low to enable the device. Drive EN high to disable the device
12	GND	Ground	Connect to PCB ground plane
13			
14	V _{BUS_SYS}	I	Connect to internal V _{BUS} plane
15			
16	NC	NC	No connect, leave floating or connect to ground. Do not connect to V _{BUS_CON}

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) ⁽¹⁾ ⁽²⁾

		MIN	MAX	UNIT
V _{BUS_CON}	Supply voltage from USB connector	- 0.3	18	V
V _{BUS_SYS}	Internal supply DC voltage rail on the PCB	- 0.3	6	V
VD+, VD -	Voltage range from connector-side USB data lines	- 0.3	18	V
D+, D -	Voltage range for internal USB data lines	- 0.3	V _{IN} + 0.3	V
V _{IN}	Voltage range for V _{IN} supply input	- 0.3	4	V
EN	Voltage on enable pin		7	V
T _A	Operating free air temperature	- 40	125	°C
T _{STG}	Storage temperature	- 65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum.

6.2 ESD Ratings—AEC Specification

		VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per AEC Q100-002 ⁽¹⁾	±4000
		Charged-device model (CDM), per AEC Q100-011	±1500

- (1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

6.3 ESD Ratings—IEC Specification

			VALUE	UNIT
V _(ESD)	Electrostatic discharge	IEC 61000-4-2, V _{BUS_CON} , VD+, VD - pins	Contact discharge ⁽¹⁾	±8000
			Air-gap discharge ⁽¹⁾	±15000

- (1) See the [ESD System Test Setup](#) diagram for details on system level ESD testing setup.

6.4 ESD Ratings—ISO Specification

			VALUE	UNIT
V _(ESD)	Electrostatic discharge	ISO 10605 (330 pF, 330 Ω), V _{BUS_CON} , VD+, VD - pins	Contact discharge ⁽¹⁾	±8000
			Air-gap discharge ⁽¹⁾	±15000

- (1) See the [ESD System Test Setup](#) diagram for details on system level ESD testing setup.

6.5 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V _{BUS_CON}	Supply voltage from USB connector			5.25	V
V _{BUS_SYS}	Internal supply DC voltage rail on the PCB	4.75		5.25	V
VD+, VD -	Voltage range from connector-side USB data lines	0	V _{IN} + 0.3		V
D+, D -	Voltage range for internal USB data lines	0	V _{IN} + 0.3		V
V _{IN}	Voltage range for V _{IN} supply	3		3.6	V
I _{BUS}	Current through V _{BUS} switch			500	mA
EN	Voltage range for enable	0		5.9	V

6.5 Recommended Operating Conditions (continued)

over operating free-air temperature range (unless otherwise noted)

			MIN	NOM	MAX	UNIT
C _{SYS}	Input capacitance ⁽¹⁾	V _{BUS_SYS} pin		100		μF
C _{LOAD}	Output load capacitance ⁽¹⁾	V _{BUS_CON} pin	1			μF
C _{VIN}	V _{IN} capacitance ⁽¹⁾	V _{IN} pin	1			μF

(1) See [Figure 9-1](#) for configuration details

6.6 Thermal Information

THERMAL METRIC ⁽¹⁾		TPD3S714-Q1	UNIT
		DBQ (SSOP)	
		16 PINS	
θ _{JA}	Junction-to-ambient thermal resistance	98.8	°C/W
θ _{JCTop}	Junction-to-case (top) thermal resistance	48	°C/W
θ _{JB}	Junction-to-board thermal resistance	41.6	°C/W
ψ _{JT}	Junction-to-top characterization parameter	8.5	°C/W
ψ _{JB}	Junction-to-board characterization parameter	41.2	°C/W
θ _{JCbot}	Junction-to-case (bottom) thermal resistance	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

6.7 Electrical Characteristics

over operating free-air temperature range, $\overline{EN} = 0$ V, V_{BUS_SYS} = 5 V, V_{IN} = 3.3 V, VD+/VD- /D+/D- /V_{BUS_CON} = float (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
SUPPLY CURRENT CONSUMPTION							
I _{VBUS_SLEEP}	V _{BUS} sleep current consumption	Measured at V _{BUS_SYS} pin, $\overline{\text{EN}} = 5\text{ V}$		45	150		μA
I _{VBUS}	V _{BUS} operating current consumption	Measured at V _{BUS_SYS} pin		285	380		μA
I _{VIN}	Leakage current for V _{IN}	Measured at V _{IN} pin, V _{IN} = 3.6 V		12	25		μA
I _{ON(LEAK)}	Leakage through V _{BUS} while shorted to battery and powered on	Measured flowing in to V _{BUS_SYS} pin, V _{BUS_SYS} = 5 V, V _{BUS_CON} = 18 V			120		μA
I _{OFF(LEAK)}	Leakage through V _{BUS} while shorted to battery and unpowered	Measured flowing out of V _{BUS_SYS} pin, V _{BUS_SYS} = 0 V, V _{BUS_CON} = 18 V			50		μA
I _{VD(OFF_LEAK)}	Leakage into data path while shorted to battery and unpowered	Measured flowing in to VD+ or VD− pins, V _{BUS_SYS} = 0 V, VD+ or VD− = 18 V, V _{IN} = 0 V, D+/D− = 0 V			80		μA
I _{VD(ON_LEAK)}	Leakage into data path while shorted to battery and powered on	Measured flowing in to VD+ or VD− pins, V _{BUS_SYS} = 5 V, VD+ or VD− = 18 V, D+/D− = 0 V			80		μA
V _{IN} PIN							
V _{UVLO(RISING)}	Undervoltage lockout rising for V _{IN}	V _{IN}	Ramp V _{IN} down until FLT is deasserted, $\overline{\text{EN}} = 5\text{ V}$	2.6	2.7	2.9	V
V _{UVLO(FALLING)}	Undervoltage lockout falling for V _{IN}		Ramp V _{IN} until FLT is asserted, $\overline{\text{EN}} = 5\text{ V}$	2.5	2.6	2.8	
EN, FLT PINS							
V _{IH}	High-level input voltage	EN	Set EN = 0 V; Sweep EN to 1.4 V; Measure when FLT is asserted	1.2			V
V _{IL}	Low-level input voltage	EN	Set EN = 3.3 V; Sweep EN from 3.3 V to 0.5 V; Measure when FLT is deasserted			0.8	V
I _{IL}	Input leakage current	EN	V _(EN) = 3.3 V ; Measure Current into EN pin			1	μA
V _{OL}	Low-level output voltage	FLT	I _{OL} = 3 mA			0.4	V
OCP CIRCUIT—V _{BUS}							

6.7 Electrical Characteristics (continued)

over operating free-air temperature range, $\overline{EN} = 0$ V, $V_{BUS_SYS} = 5$ V, $V_{IN} = 3.3$ V, $VD+/VD- / D+/D- / V_{BUS_CON} = \text{float}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
I_{LIM}	Overcurrent limit	V_{BUS}	Progressively load V_{BUS_CON} until device asserts FLT	550	700	850	mA
OVERTEMPERATURE PROTECTION							
$T_{SD(RISING)}$	The rising overtemperature protection shutdown threshold	$V_{BUS_SYS} = 5$ V, $\overline{EN} = 0$ V, No Load on V_{BUS_CON} , T_A stepped up until FLT is asserted		150	165	180	°C
$T_{SD(FALLING)}$	The falling overtemperature protection shutdown threshold	$V_{BUS_SYS} = 5$ V, $\overline{EN} = 0$ V, No Load on V_{BUS_CON} , T_A stepped down from $T_{SD(RISING)}$ until FLT is deasserted		125	130	140	°C
$T_{SD(HYST)}$	The overtemperature protection shutdown threshold hysteresis	$T_{SD(RISING)} - T_{SD(FALLING)}$		10	35	55	°C
OVP CIRCUIT—V_{BUS}							
$V_{OVP(RISING)}$	Input overvoltage protection threshold	V_{BUS_CON}	Increase V_{BUS_CON} from 5 V to 7 V. Measure when FLT is asserted	5.4	5.6	5.8	V
$V_{HYS(OVP)}$	Hysteresis on OVP	V_{BUS_CON}	Difference between rising and falling OVP thresholds on V_{BUS_CON}		50		mV
$T_{OVP(FALLING)}$	Input overvoltage protection threshold	V_{BUS_CON}	Decrease V_{BUS_CON} from 7 V to 5 V. Measure when FLT is deasserted	5.36		5.74	V
$V_{UVLO(SYS_RISING)}$	Undervoltage lockout rising for V_{BUS_SYS}	V_{BUS_SYS}	V_{BUS_SYS} voltage rising from 0 V to 5 V	3.1	3.3	3.6	V
$V_{HYS(UVLO_SYS)}$	V_{BUS_SYS} UVLO hysteresis	V_{BUS_SYS}	Difference between rising and falling UVLO thresholds on V_{BUS_SYS}	50	75	100	mV
$V_{UVLO(SYS_FALLING)}$	Undervoltage lockout falling for V_{BUS_SYS}	V_{BUS_SYS}	V_{BUS_SYS} voltage falling from 7 V to 3 V	3	3.2	3.5	V
$V_{SHRT(RISING)}$	Short-to-ground comparator rising threshold	V_{BUS_CON}	Increase V_{BUS_CON} voltage from 0 V until the device transitions from the short-circuit to over-current mode of operation	2.5	2.6	2.7	V
$V_{SHRT(FALLING)}$	Short-to-ground comparator falling threshold	V_{BUS_CON}	Set $V_{BUS_SYS} = 5$ V; $V_{IN} = 3.3$ V; $\overline{EN} = 0$ V; Decrease V_{BUS_CON} voltage from 5 V until the device transitions from the overcurrent to short-circuit mode of operation	2.4	2.5	2.6	V
$V_{SHRT(HYST)}$	Short-to-ground comparator hysteresis	V_{BUS_CON}	Difference between $V_{SHRT(RISING)}$ and $V_{SHRT(FALLING)}$	100	125	150	mV
I_{SHRT}	Short-to-ground current source	V_{BUS_CON}	Current sourced from V_{BUS_SYS} when device is in short-circuit mode	150		350	mA
OVP CIRCUIT—$VD+/VD-$							
$V_{OVP(RISING)}$	Input overvoltage protection threshold	$VD+/VD-$	Increase $VD+$ or $VD-$ (with $D+$ and $D-$) from 3.3 V to 4.5 V. Measure the value at which FLT is asserted	$V_{IN} + 0.6$	$V_{IN} + 0.8$	$V_{IN} + 1$	V
$V_{HYS(OVP)}$	Hysteresis on OVP	$VD+/VD-$	Difference between rising and falling OVP thresholds on $VD+/VD-$		50		mV
$V_{OVP(FALLING)}$	Input overvoltage protection threshold	$VD+/VD-$	Decrease $VD+$ or $VD-$ (with $D+$ or $D-$) from 4.5 V to 2 V. Measure the value at FLT is deasserted	$V_{IN} + 0.525$	$V_{IN} + 0.75$	$V_{IN} + 0.975$	V
SHORT-TO-BATTERY							
$V_{(VBUS_STB)}$	V_{BUS} hotplug short-to-battery tolerance	V_{BUS_CON}	Charge battery-equivalent capacitor to test voltage then discharge to pin under test through a 1-meter, 18-gauge wire. (See Figure 7-1 for more details)			18	V
$V_{(DATA_STB)}$	Data line hotplug short-to-battery tolerance	$VD+/VD-$				18	V
DATA LINE SWITCHES—$VD+$ to $D+$ or $VD-$ to $D-$							
C_{ON}	Equivalent on capacitance		Capacitance of $D+/D-$ switches when enabled - measure on connector side across bias voltage 0 V to 0.4 V		6.2		pF
R_{ON}	On resistance		Measure resistance between $D+$ and $VD+$ or $D-$ and $VD-$, voltage between 0 and 0.4 V		4	6.5	Ω
$R_{ON(Flat)}$	On resistance flatness		Measure resistance between $D+$ and $VD+$ or $D-$ and $VD-$, sweep voltage between 0 V and 0.4 V		0.2	1	Ω

6.7 Electrical Characteristics (continued)

over operating free-air temperature range, $\overline{EN} = 0\text{ V}$, $V_{BUS_SYS} = 5\text{ V}$, $V_{IN} = 3.3\text{ V}$, $VD+/VD- / D+/D- / V_{BUS_CON} = \text{float}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
BW_{ON}	On bandwidth (- 3 dB)	Measure S_{21} bandwidth from D+ to VD+ or D - to VD - with voltage swing = 400 mVpp, $V_{CM} = 0.2\text{ V}$		860		MHz
BW_{ON_DIFF}	On bandwidth (- 3 dB)	Measure S_{DD21} bandwidth from D+ to VD+ and D - to VD - with voltage swing = 800 mVpp differential, $V_{CM} = 0.2\text{ V}$		1050		MHz
X_{talk}	Crosstalk	Measure S_{21} bandwidth from D+ to VD - or D - to VD+ with voltage swing = 400 mVpp. Be sure to terminate open sides to 50 ohms. $f = 480\text{ MHz}$		- 34		dB
nFET SWITCH—VBus						
$R_{(DISCHARGE)}$	Output discharge resistance	$\overline{EN} = 5\text{ V}$, Set $V_{BUS_CON} = 5\text{ V}$ and measure current flow to ground			12500	Ω
R_{ON}	Switch ON resistance	$V_{BUS_CON} = 5\text{ V}$, $I_{OUT} = 0.5\text{ A}$		63	150	m Ω

6.8 Timing Requirements

over operating free-air temperature range, $\overline{EN} = 0\text{ V}$, $V_{BUS_SYS} = 5\text{ V}$, $V_{IN} = 3.3\text{ V}$, $VD+/VD- /D+/D- /V_{BUS_CON} = \text{float}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
ENABLE PIN						
t_{ON}	Enable on time	Time between enable device until $\overline{FLT}$ deasserts		13		ms
OVERCURRENT PROTECTION						
t_{BLANK}	Overcurrent blanking time	Time from overcurrent condition until $\overline{FLT}$ assertion and V_{BUS} FET turnoff			2	ms
t_{RETRY}	Overcurrent retry time	Time from overcurrent FET shut off until FET turns back on		100		ms
t_{RECV}	Overcurrent recovery time	Time from end of t_{RETRY} until $\overline{FLT}$ deassertion if overcurrent condition is removed		8		ms
OVERVOLTAGE PROTECTION						
$t_{OVP_response}$	OVP response time - V_{BUS}	Measured from OVP Condition to FET turnoff		2	4	μs
$t_{OVP_response}$	OVP response time - data switches	Measured from OVP Condition to FET turnoff		200		ns
SHORT-TO-GROUND PROTECTION						
t_{SHRT}	Short to ground response time	$C_{LOAD} = 0\text{ uF}$, Time from short condition until current falls below 120% of I_{SHRT}		2	4	μs

6.9 Typical Characteristics

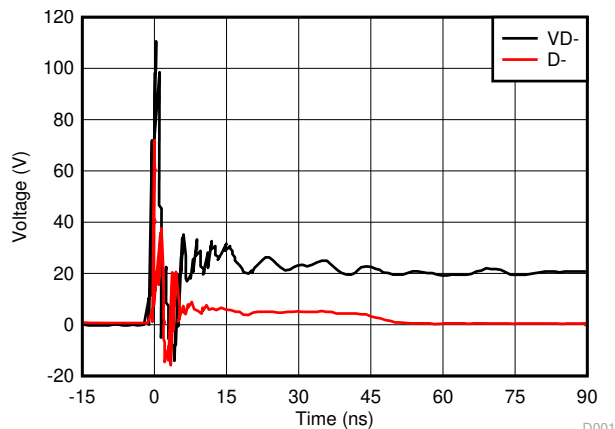


图 6-1. 8-kV IEC Contact Waveform

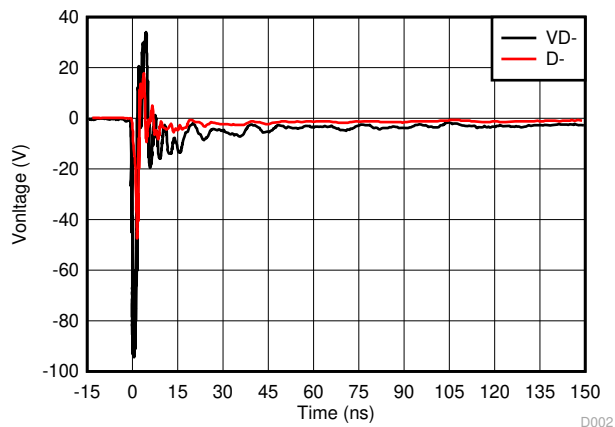


图 6-2. -8-kV IEC Contact Waveform

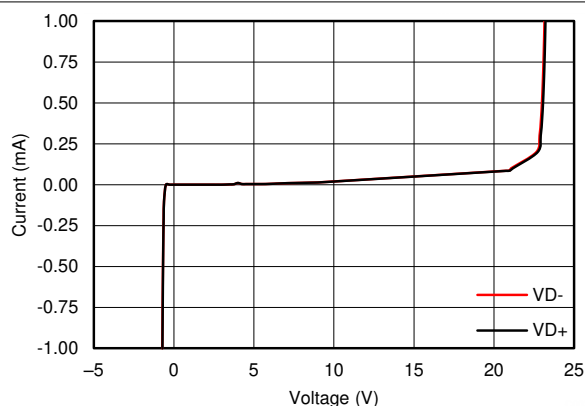


图 6-3. Data Line I-V Curve

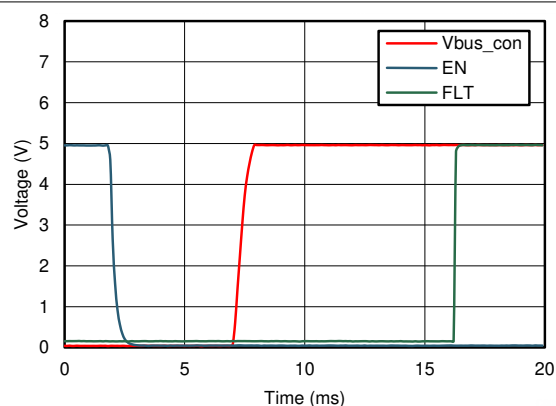


图 6-4. VBUS tON Time

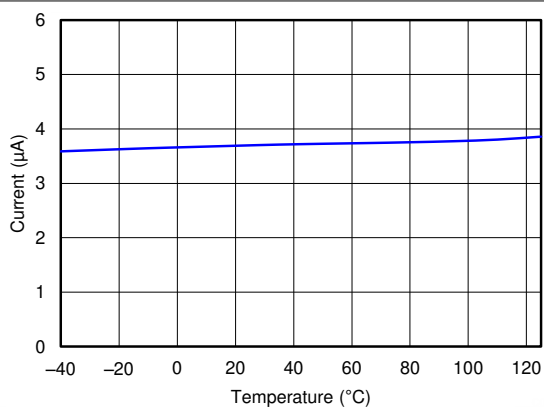


图 6-5. VD± Short-to-5 V (while Enabled) Across Temperature

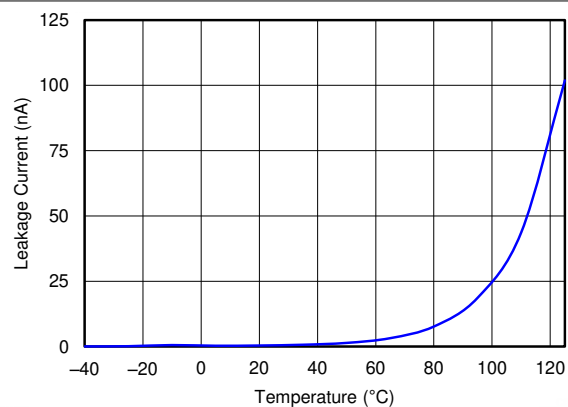
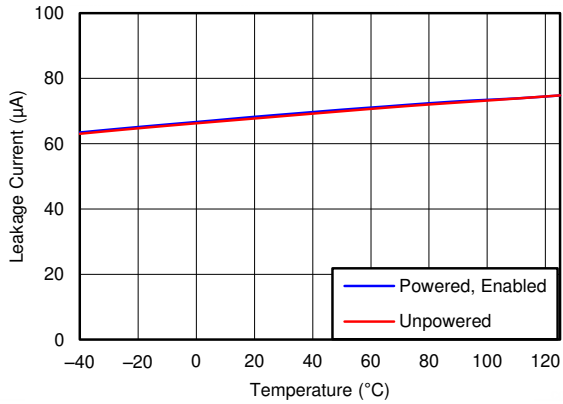
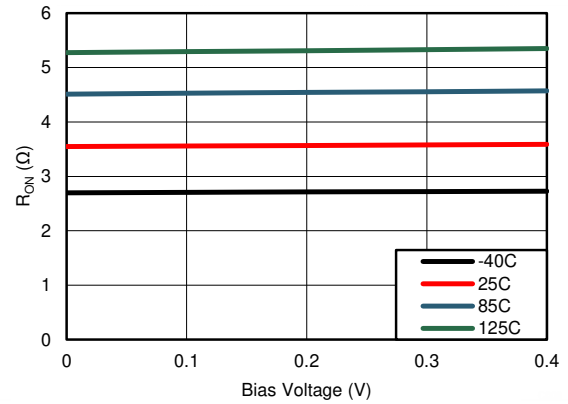
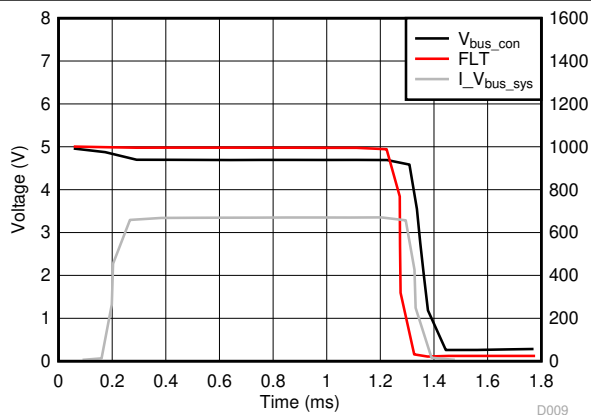
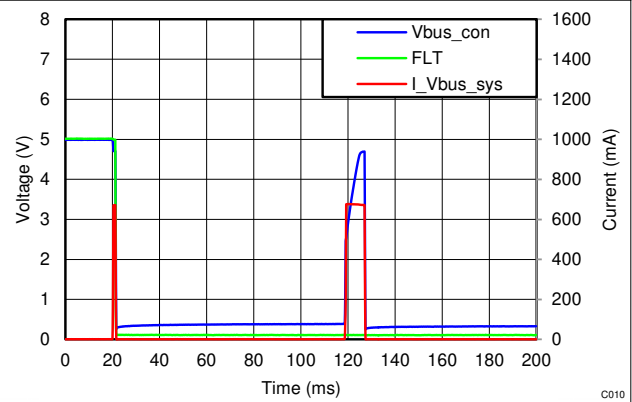
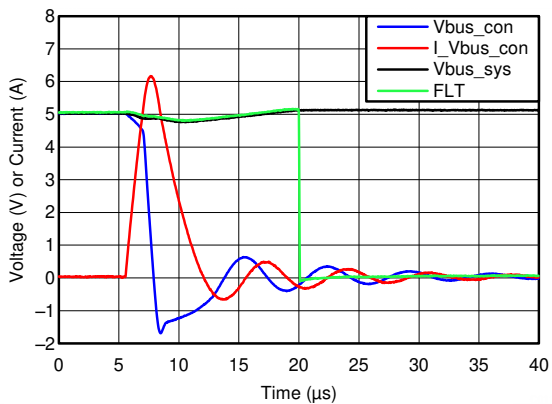
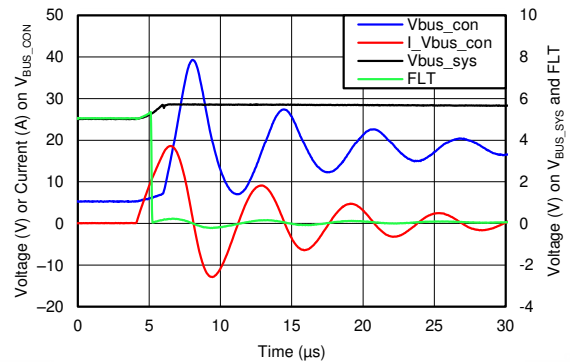


图 6-6. VD± Short-to-5 V (while Unpowered) Across Temperature

图 6-7. $VD_{\pm}$ Short-to-18 V Across Temperature图 6-8. Data Switch R_{ON} vs Bias Voltage图 6-9. Overcurrent t_{BLANK} Response Waveform图 6-10. Overcurrent t_{BLANK_RETRY} Response Waveform图 6-11. V_{BUS} Short-to-Ground Response Waveform图 6-12. V_{BUS} Short-to-18 V Response Waveform

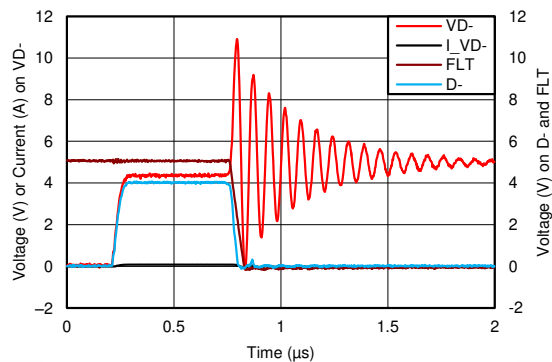


图 6-13. Data Switch Short-to-5 V Response Waveform

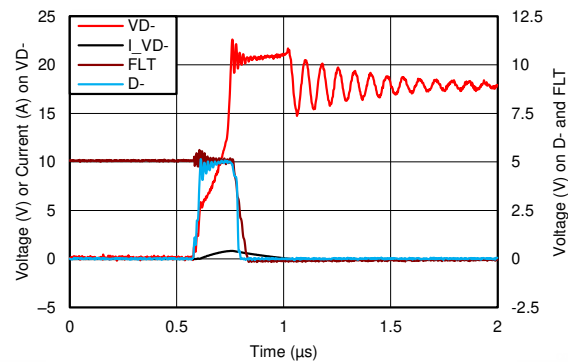


图 6-14. Data Switch Short-to-18 V Response Waveform

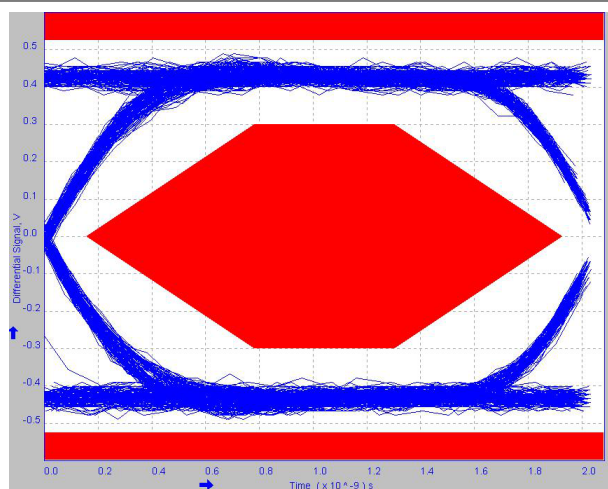


图 6-15. USB2.0 Eye Diagram (No TPD3S714-Q1)

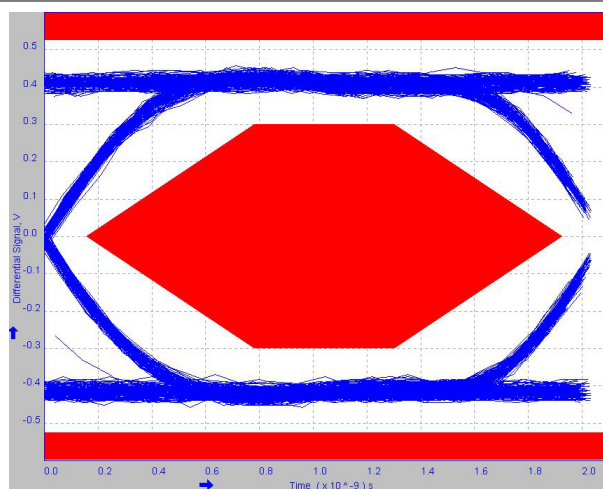


图 6-16. USB2.0 Eye Diagram (With TPD3S714-Q1)

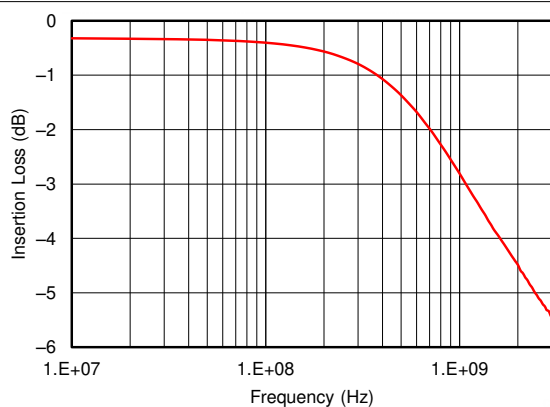


图 6-17. Data Switch Differential Bandwidth

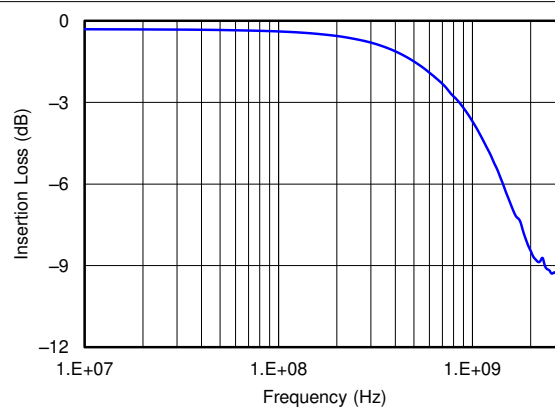


图 6-18. Data Switch Single-Ended Bandwidth

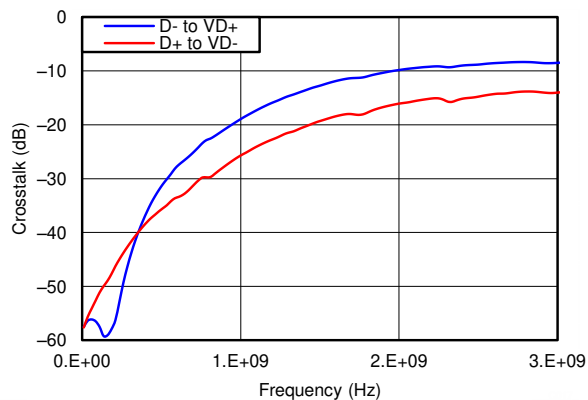
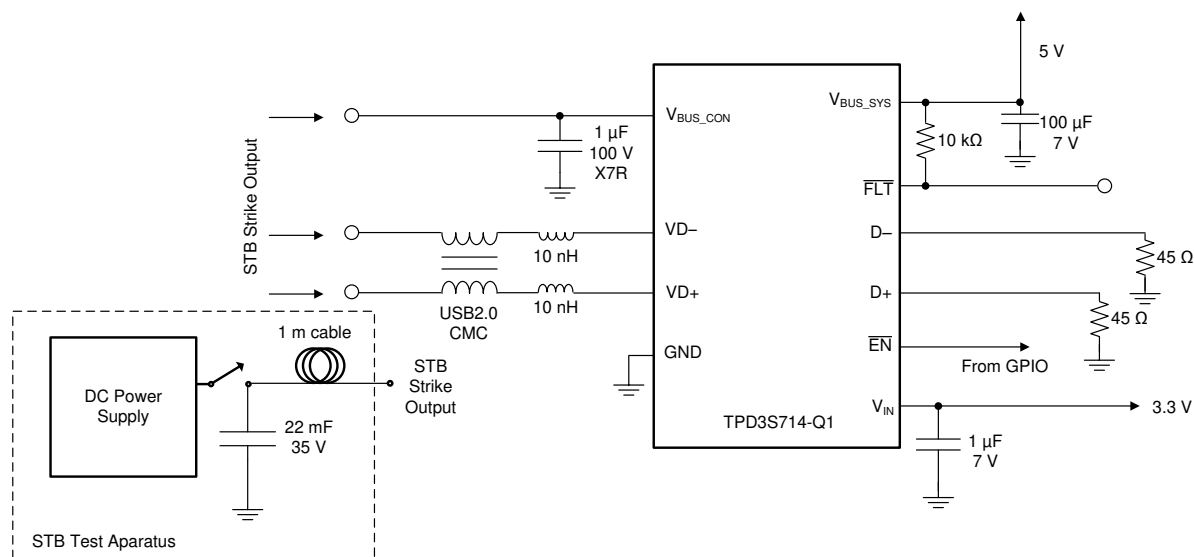


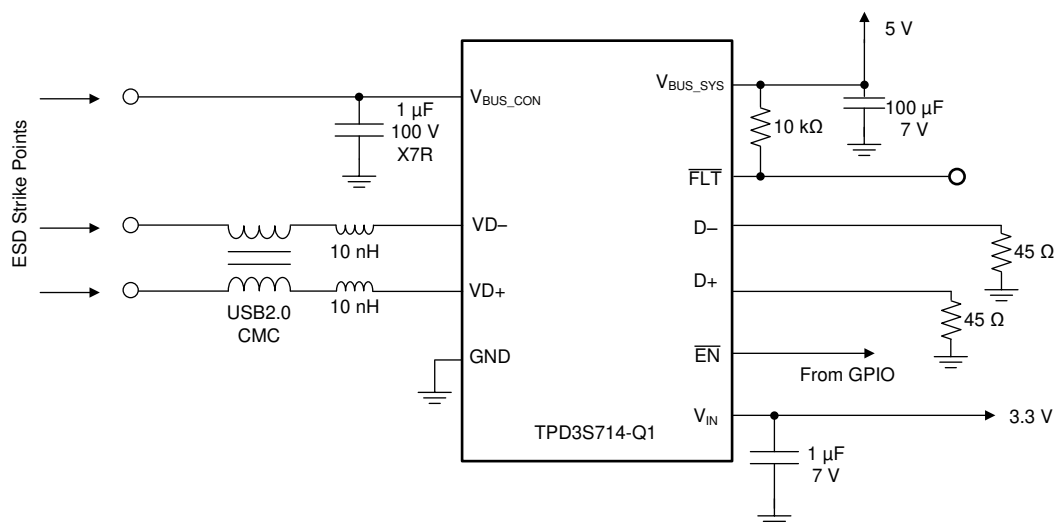
图 6-19. Data Switch Crosstalk

7 Parameter Measurement Information



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图 7-1. Short-to-Battery System Test Setup



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图 7-2. ESD System Test Setup

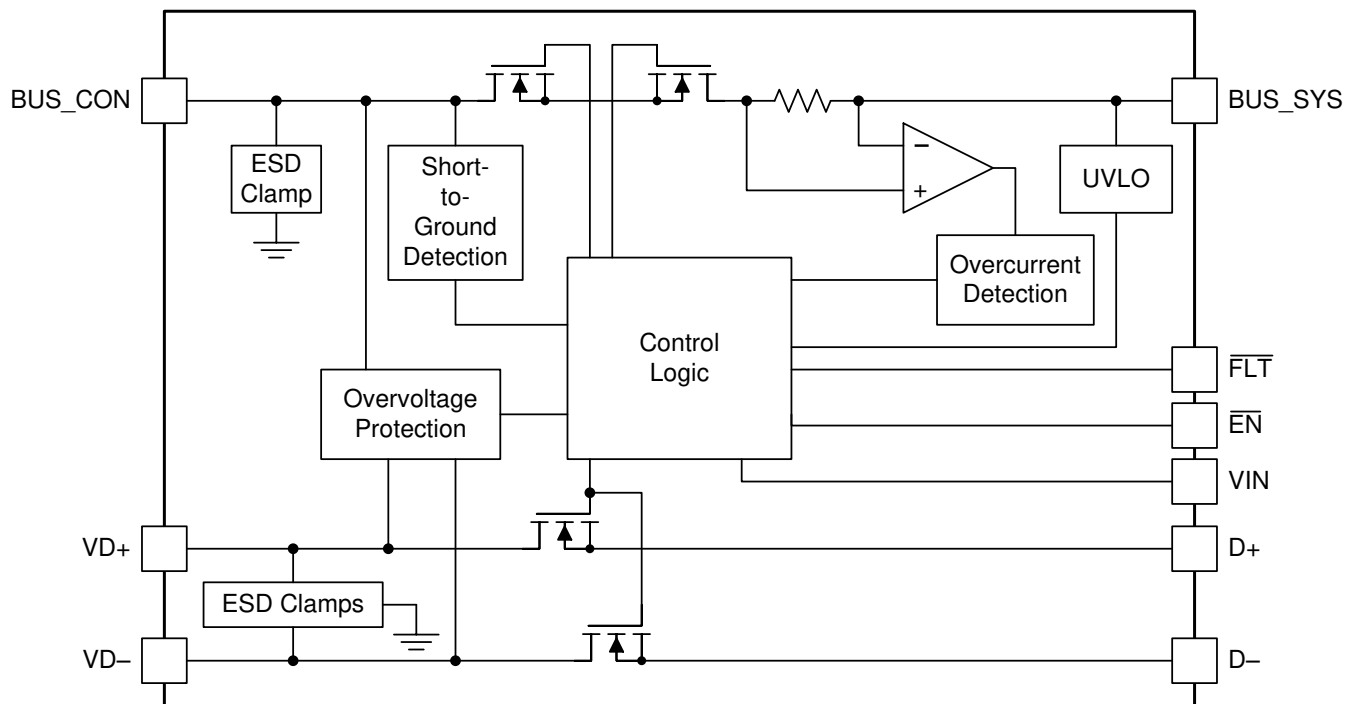
8 Detailed Description

8.1 Overview

The TPD3S714-Q1 provides a single-chip ESD protection and overvoltage protection solution for automotive USB interfaces. It offers short to battery protection up to 18 V and short to ground protection on V_{BUS_CON} . The TPD3S714-Q1 also provides a $\overline{FLT}$ pin that indicates to the system if a fault condition has occurred. The TPD3S714-Q1 offers ESD clamps on the V_{BUS_CON} , $VD+$, and $VD-$ pins, thus eliminating the need for external TVS clamp circuits in the application.

The TPD3S714-Q1 has internal circuitry that controls the turnon of the internal nFET switches. An internal oscillator controls the timers that enable the switches and resets the open-drain $\overline{FLT}$ output. If V_{BUS_CON} is less than V_{OVP} , the switches are enabled. After an internal delay, the charge-pump starts-up, turns on the internal nFET switch through a soft start. Once the nFET is completely turned ON, TPD3S714-Q1 releases $\overline{FLT}$ pin to HIGH. At any time, if any of the external pins rise above V_{OVP} , $\overline{FLT}$ pin is pulled LOW. The nFET switches are turned OFF.

8.2 Functional Block Diagram



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8.3 Feature Description

8.3.1 AEC-Q100 Qualified

The TPD3S714-Q1 is an automotive qualified device according to the AEC-Q100 standards. This device is qualified to operate from -40 to $+125^{\circ}\text{C}$ ambient temperature.

8.3.2 Short-to-Battery and Short-to-Ground Protection on V_{BUS_CON}

The V_{BUS_CON} pin is protected against shorts to battery and shorts to ground.

Once a voltage on V_{BUS_CON} is detected as too low (below the V_{SHRT} threshold) after the device is enabled, the device enters short-circuit protection mode and asserts $\overline{FLT}$. It sources the I_{SHRT} current until it detects the voltage rising above the V_{SHRT} threshold, where it resumes standard operating mode and deasserts $\overline{FLT}$.

Once a voltage above the V_{OVP} threshold is detected by the device, it shuts off all FETs and asserts a fault on the $\overline{FLT}$ pin. Once the excessive voltage is removed, the device automatically re-enables and $\overline{FLT}$ deasserts (see the [Timing Requirements](#) table for more details).

8.3.3 Short-to-Battery and Short-to- V_{BUS} Protection on $VD+$, $VD-$

The $VD+$ and $VD-$ pins are protected against shorts to battery and shorts to bus. The OVP threshold on the $VD+$ and $VD-$ pins is low enough that it protects against shorts to V_{BUS} .

Once a voltage above the V_{OVP} threshold is detected by the device, it shuts off all FETs and asserts a fault on the $\overline{FLT}$ pin. Once the excessive voltage is removed, the device automatically re-enables and $\overline{FLT}$ deasserts.

8.3.4 ESD Protection on V_{BUS_CON} , $VD+$, $VD-$

The protected pins (V_{BUS_CON} , $VD+$, $VD-$) are tested to pass the IEC 61000-4-2 ESD standard up to Level 4 ESD protection. Additionally, these pins are tested against ISO 10605 with the 330-pF, 330- Ω equivalent network. This guarantees passing of at least ± 8 -kV contact discharge and ± 15 -kV air gap discharge according to both standards using test setup shown in [Figure 7-2](#).

8.3.5 Low R_{ON} nFET V_{BUS} Switch

The V_{BUS} switch has a low R_{ON} that provides minimal voltage droop from system to connector. Typical resistance is 63 m Ω and is specified for 150 m Ω at 125°C ambient temperature.

8.3.6 High Speed Data Switches

The $D+$ and $D-$ switches have a very low capacitance and a high bandwidth (1-GHz typical), allowing for a clean USB 2.0 eye diagram.

8.3.7 Hiccup Current Limit

The V_{BUS} path of this device has an integrated overcurrent protection circuit. Above the overcurrent threshold (550-mA minimum), the device goes into a fault state where it limits current to the threshold. After a short blanking time, the device cycles on and off to try to check if the connected device is still in overcurrent.

8.3.8 Fast Overvoltage Response Time

The overvoltage FETs are designed to have a fast turnoff time to protect the upstream SoC as quickly as possible. Typical response time for complete turnoff is 2 μ s for the V_{BUS} path and 200 ns for the data path.

8.3.9 Integrated Input Enable

The TPD3S714-Q1 has an enable input to turn on and off the device. The $\overline{EN}$ pin disables and enables the V_{BUS} and data paths.

8.3.10 Fault Output Signal

The TPD3S714-Q1 has a fault pin, $\overline{FLT}$ that indicates when there is any sort of fault condition because of OVP, OCP, or short-circuit.

8.3.11 Thermal Shutdown Feature

In the event that the device exceeds the maximum allowable junction temperature, it shuts down the device to prevent damage to itself and indicate via the fault pin.

8.3.12 16-pin SSOP Package

This device is packaged in a standard 16-pin SSOP leaded package.

8.4 Device Functional Modes

8.4.1 Normal Operation

The TPD3S714-Q1 operates normally (all FETs on) when enabled, both V_{BUS_SYS} and V_{IN} are above their UVLO thresholds, and the device is not in any fault conditions.

8.4.2 Overvoltage Condition

When the $VD+$, $VD-$, or V_{BUS_CON} pins exceed their OVP threshold, the device enters the overvoltage state. All FETs are disabled and the $\overline{FLT}$ pin is asserted. Once the protected pins drop below their OVP threshold, the device automatically turns back on.

8.4.3 Overcurrent Condition

When the current through the V_{BUS} path exceeds the I_{LIM} current threshold, the device enters into the overcurrent state. The TPD3S714-Q1 limits current to the I_{LIM} threshold by dropping voltage across the V_{BUS} FET to maintain constant current. Once it continues to sense an overcurrent condition for the blanking time t_{BLANK} , the device disables itself for the retry time, t_{RETRY} and then retry automatically for the retry time, t_{BLANK_RETRY} . In the event that the current is below the overcurrent threshold, the device deasserts fault and resumes normal operation.

8.4.4 Short-Circuit Condition

When the voltage on the V_{BUS_CON} side drops below the V_{SHRT} threshold while enabled, the TPD3S714-Q1 enters the short-circuit mode. It sources a constant current of I_{SHRT} until it rises above the V_{SHRT} threshold. Once that occurs, the device automatically re-enters normal operation and deasserts fault.

8.4.5 Device Logic Tables

表 8-1 shows the TPD3S714-Q1 V_{BUS} Logic Table.

表 8-1. TPD3S714-Q1 V_{BUS} Logic Table

VOLTAGE CONDITION			CURRENT CONDITION		
V_{BUS_CON}	V_{BUS_SYS}	$\overline{EN}$	CURRENT FLOW	COMMENT	FLT PIN
X	<UVLO	X	No Flow	Switch off because of UVLO	High-Z
<OVP and > V_{SHRT}	>UVLO	Low	V_{BUS_SYS} to V_{BUS_CON}	Current flows through the switch, normal host mode	High-Z
X	>UVLO	High	No Flow	Switch off	Low
< V_{SHRT}	>UVLO	Low	V_{BUS_SYS} to V_{BUS_CON}	Current flow through switch, device detects short circuit, current limited to I_{SHRT}	Low
X	X	Low	>OCP	Device switches off because of overcurrent limit, auto-retrys until <OCP or thermal shutdown conditions occur	Low
>OVP	>UVLO	Low	No Flow	Switch off because of OVP	Low
X	X	X	No Flow	Thermal Shutdown Condition	Low

表 8-2 shows the TPD3S714-Q1 Data Line Logic Table

表 8-2. TPD3S714-Q1 Data Line Logic Table

VOLTAGE CONDITION		CURRENT CONDITION		
$VD+/VD-$	$\overline{EN}$	SWITCHES ON?	COMMENT	FLT PIN
<OVP	Low	Yes	Device operates normally, data transfer can occur	High-Z
X	High	No	Switches off	Low
>OVP	Low	No	Switches off because of OVP limit	Low
X	X	No	Thermal Shutdown Condition	Low

9 Application and Implementation

Note

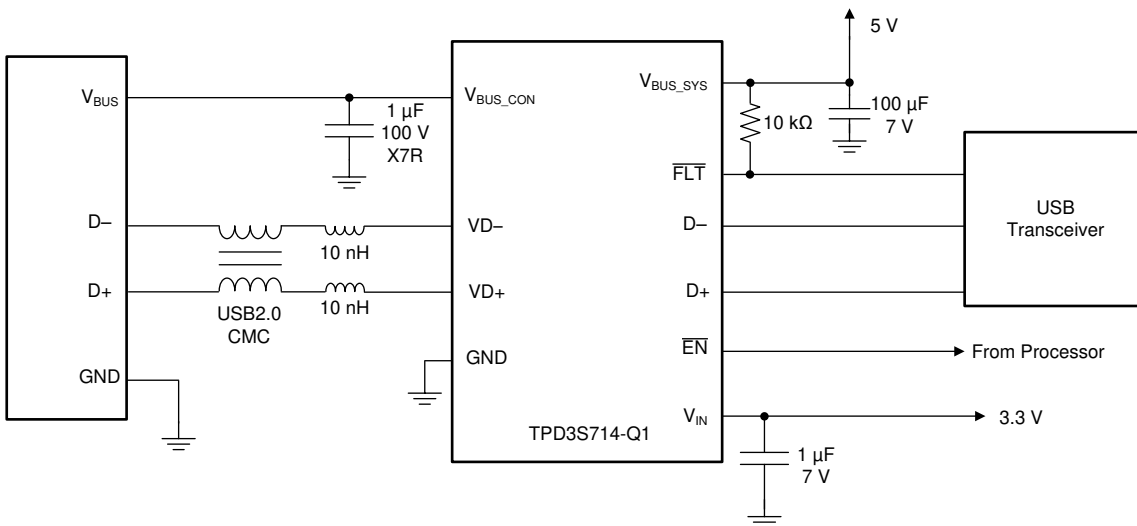
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

The TPD3S714-Q1 offers fully featured automotive USB2.0 protection including short-to-battery, overcurrent, and ESD protection. Care must be taken during the implementation to make sure the device provides adequate protection to the system.

9.2 Typical Application

图 9-1 shows a fully featured USB2.0 high speed port, with an 18-V short-to-battery requirement on the connector side.



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图 9-1. Typical Application Configuration for TPD3S714-Q1

9.2.1 Design Requirements

For this design example, the input parameters shown in 表 9-1 are used:

表 9-1. Design Parameters

DESIGN PARAMETER	EXAMPLE VALUE
Short-to-battery tolerance on VD ⁺ , VD ⁻ , V _{BUS_CON}	18 V
Maximum current in normal operation on V _{BUS}	500 mA
USB data rate	480 Mbps

9.2.2 Detailed Design Procedure

To begin the design process, the designer must know the following parameters:

- Short-to-Battery tolerance on connector pins
- Maximum current in normal operation on V_{BUS}
- USB Data Rate

9.2.2.1 Short-to-Battery Tolerance

The TPD3S714-Q1 is capable of handling up to 18-V DC on the $VD+$, $VD-$, and V_{BUS_CON} pins. In the event of a short-to-battery on V_{BUS_CON} , significant ringing is expected because of the hot plug-like nature of the short-to-battery event. In typical ceramic capacitor configurations, a standard RLC response is expected which results in a ringing of nearly two times the applied DC voltage. The TPD3S714-Q1 is capable of withstanding the transient ringing from hot plug-like events, assuming some precautions are taken.

Careful capacitor selection on the V_{BUS_CON} pin must be observed. A capacitor with a low derating percentage under the applied voltages must be used to prevent excess ringing. In the example, a 1- μ F 100-V tolerant ceramic X7R capacitor is used. It is best practice to carefully select the capacitors used in this circuit to prevent derating-based voltage spikes under hot plug events. See the application example graphs, [Figure 9-4](#) and [Figure 9-5](#) to compare ringing of a 100-V capacitor to a 50-V capacitor. [Figure 9-6](#) shows the 100-V capacitor with the TPD3S714-Q1 installed.

Another alternative to a high rated ceramic capacitor is to implement either a standard R-C snubber circuit, or a small external TVS diode. Depending on the short-to-battery tolerance needed, no special precautions may be needed.

For more information on this topic, see the white paper [Designing USB for short-to-battery tolerance in automotive environments](#).

9.2.2.2 Maximum Current on V_{BUS}

The TPD3S714-Q1 is capable of operating up to 5500 mA of current (minimum) until going into current limit mode. In this example, the maximum current for USB2.0 of 500 mA has been chosen.

9.2.2.3 USB Data Rate

The TPD3S714-Q1 is capable of operating at the maximum USB2.0 High Speed data rate of 480 Mbps because of the high data switch bandwidth of 1 GHz (typical). In this design example the maximum data rate of 480 Mbps has been chosen.

9.2.3 Application Curves

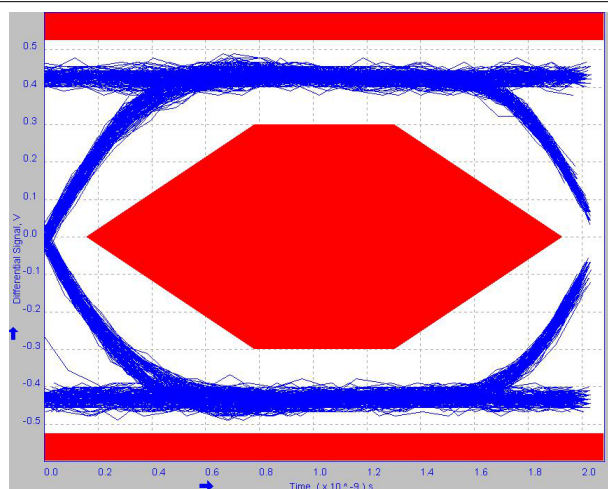


图 9-2. USB2.0 Eye Diagram (Board Only, Through Path)

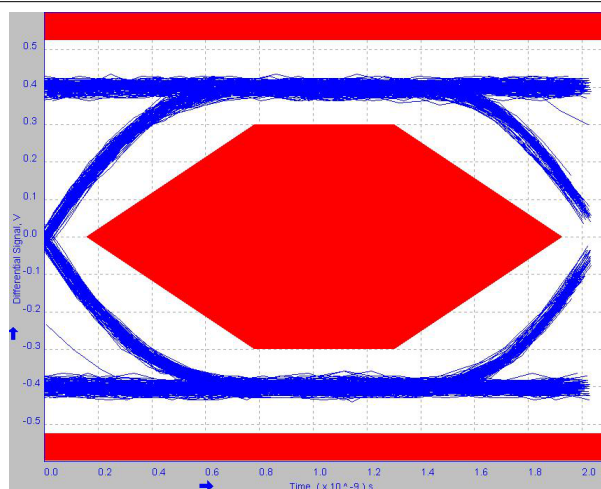


图 9-3. USB2.0 Eye Diagram (System from Typical Application Schematic)

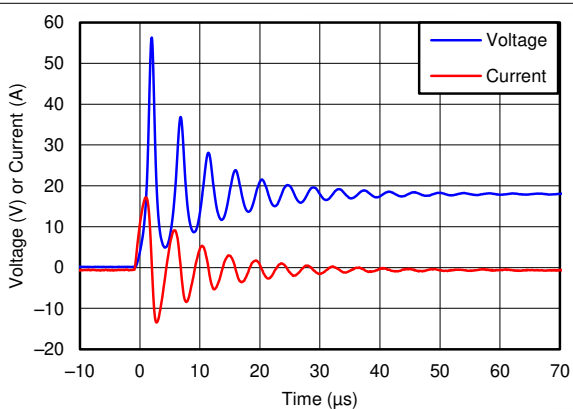


图 9-4. 50-V, 1-μF X7R Ceramic Shorted to 18-V (Not Recommended)

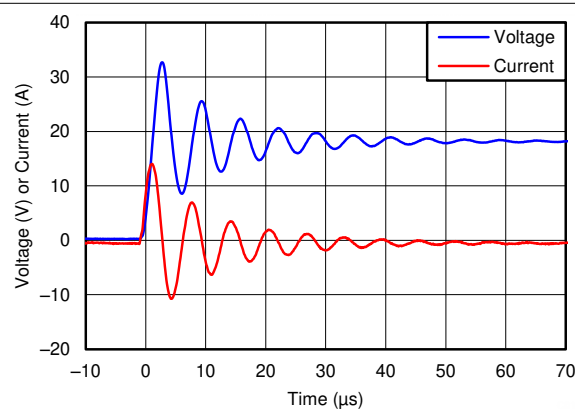


图 9-5. 100-V, 1-μF X7R Ceramic Shorted to 18 V

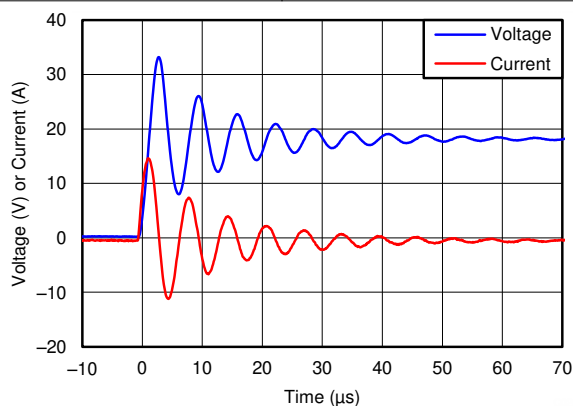


图 9-6. TPD3S714-Q1 and 100-V, 1-μF X7R Shorted to 18 V (Powered Off)

10 Power Supply Recommendations

10.1 V_{BUS} Path

The V_{BUS_SYS} pins provide power to the chip and supply current through the load switch to V_{BUS_CON}. A 100-μF bulk capacitor is recommended on V_{BUS_SYS} to supply the USB port and maintain compliance. A 1-μF capacitor is recommended on the V_{BUS_CON} pin with adequate voltage rating to tolerate short-to-battery conditions. A supply voltage above the UVLO threshold for V_{BUS_SYS} must be supplied for the device to power on.

10.2 V_{IN} Pin

The V_{IN} pin provides a voltage reference for the data switch OVP level as well as a bypass for ESD clamping. A 1-μF capacitor must be placed as close to the pin as possible and the supply must be set to be above the UVLO threshold for V_{IN}.

11 Layout

11.1 Layout Guidelines

Proper routing and placement maintains signal integrity for high-speed signals. The following guidelines apply to the TPD3S714-Q1:

- Place the bypass capacitors as close as possible to the V_{IN} , V_{BUS_SYS} , and V_{BUS_CON} pins. Capacitors must be attached to a solid ground. This minimizes voltage disturbances during transient events such as short-to-battery, ESD, or overcurrent conditions.
- High speed traces (data switch path) must be routed as straight as possible and any sharp bends must be minimized.

Our standard ESD recommendations apply to the $VD+$, $VD-$, and V_{BUS_CON} pins as well:

- The optimum placement is as close to the connector as possible.
 - EMI during an ESD event can couple from the trace being struck to other nearby unprotected traces, resulting in early system failures.
 - The PCB designer must minimize the possibility of EMI coupling by keeping any unprotected traces away from the protected traces which are between the TVS and the connector.
- Route the protected traces as straight as possible.
- Eliminate any sharp corners on the protected traces between the TVS and the connector by using rounded corners with the largest radii possible.
 - Electric fields tend to build up on corners, increasing EMI coupling.

11.2 Layout Example

Figure 11-1 shows a full layout for a standard USB2.0 port. A common mode choke and inductors are used on the high speed data lines, and the requisite bypassing caps are placed on V_{BUS_CON} , V_{BUS_SYS} , and V_{IN} .

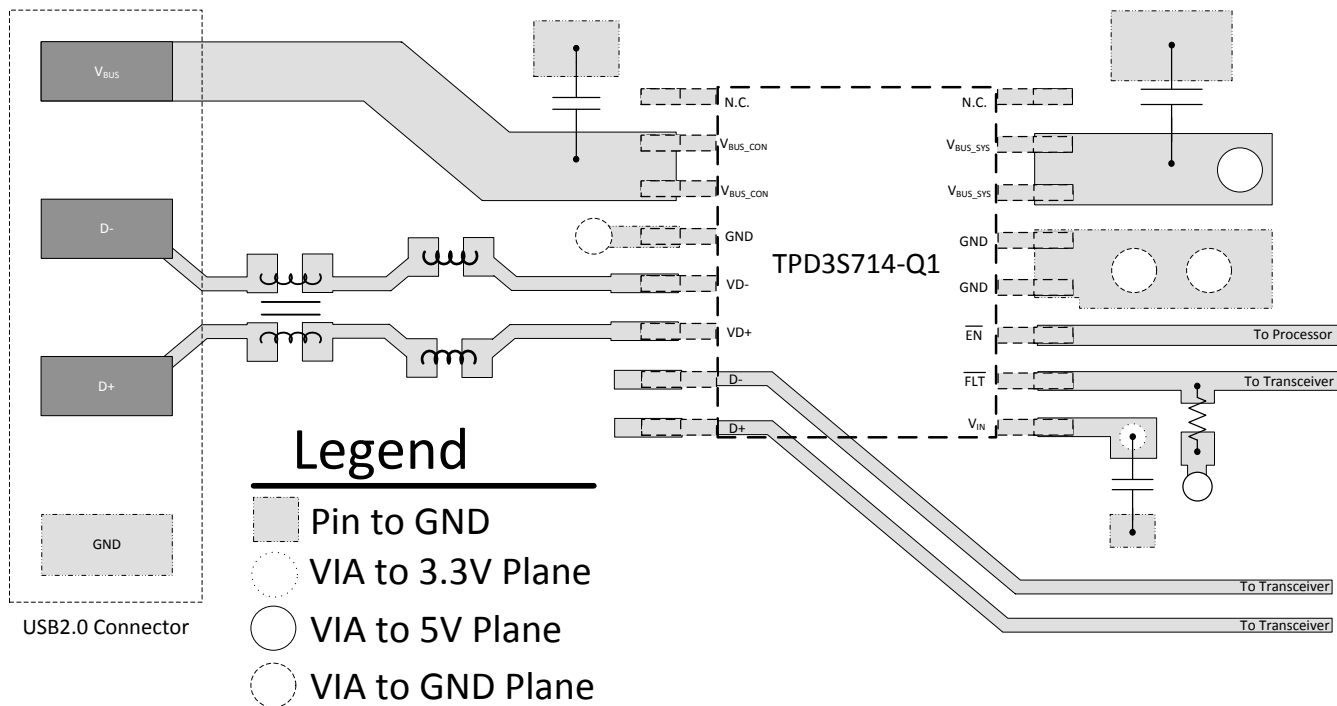


图 11-1. Typical Layout Example for TPD3S714-Q1

12 Device and Documentation Support

12.1 Documentation Support

12.1.1 Related Documentation

For related documentation see the following:

- [TPD3S714-Q1EVM User's Guide](#)
- [Reading and Understanding an ESD Protection Datasheet](#)
- [ESD Layout Guide](#)

12.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

12.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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12.4 Trademarks

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12.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

12.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

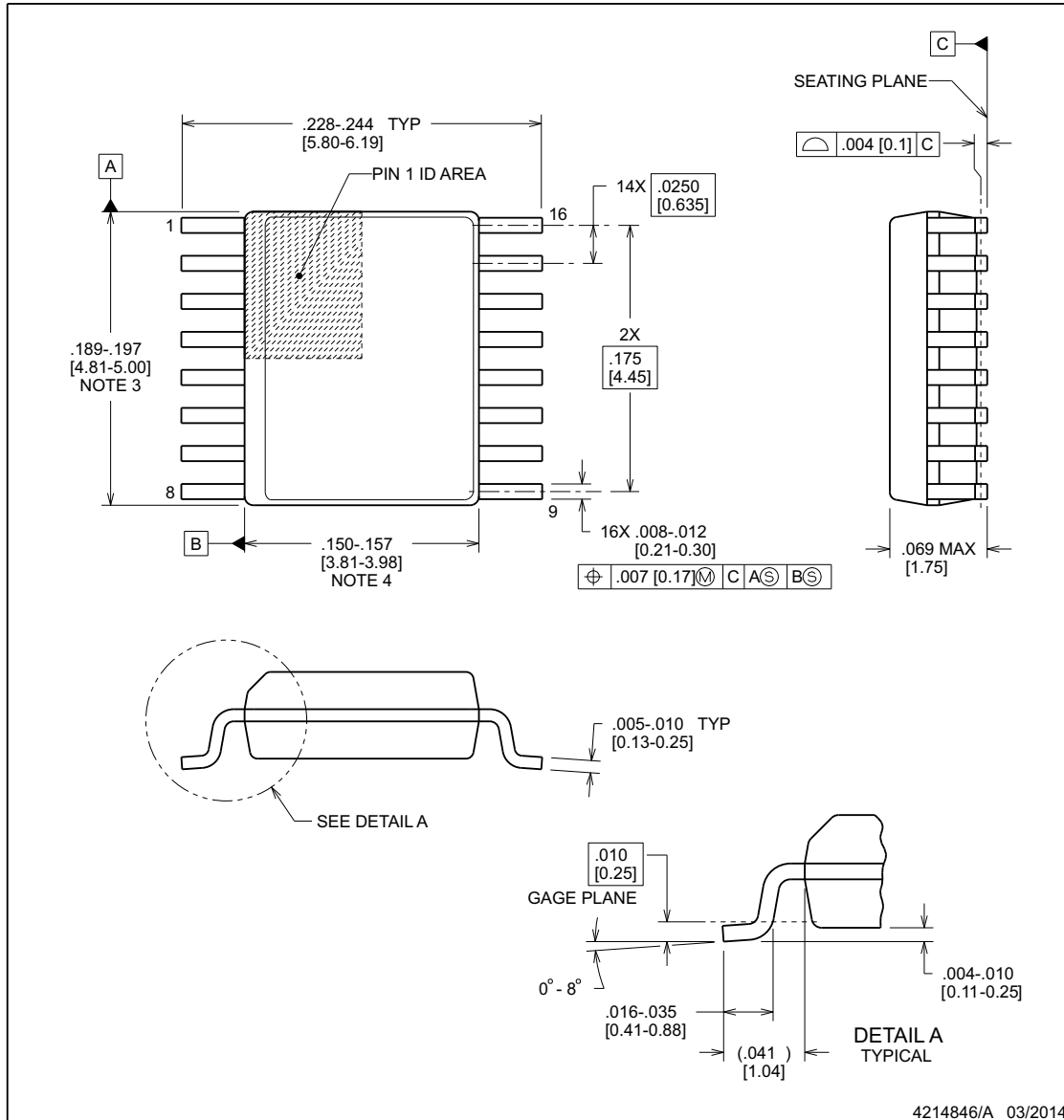
The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.



DBQ0016A

PACKAGE OUTLINE SSOP - 1.75 mm max height

SHRINK SMALL-OUTLINE PACKAGE



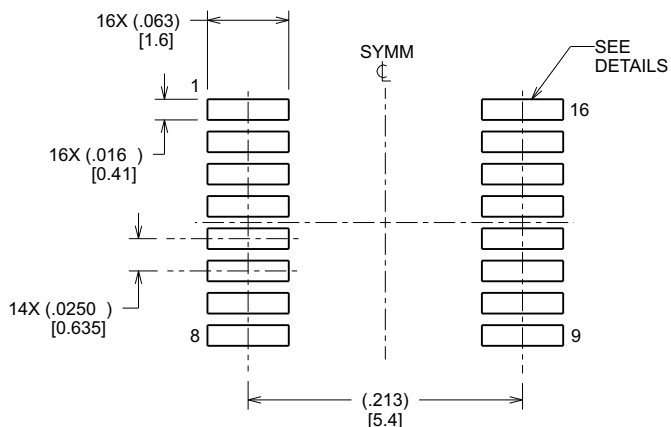
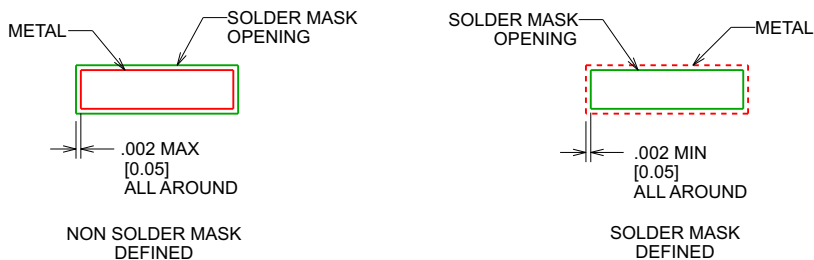
NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 inch, per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MO-137, variation AB.

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EXAMPLE BOARD LAYOUT**DBQ0016A****SSOP - 1.75 mm max height**

SHRINK SMALL-OUTLINE PACKAGE

LAND PATTERN EXAMPLE
SCALE:8X

SOLDER MASK DETAILS

4214846/A 03/2014

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

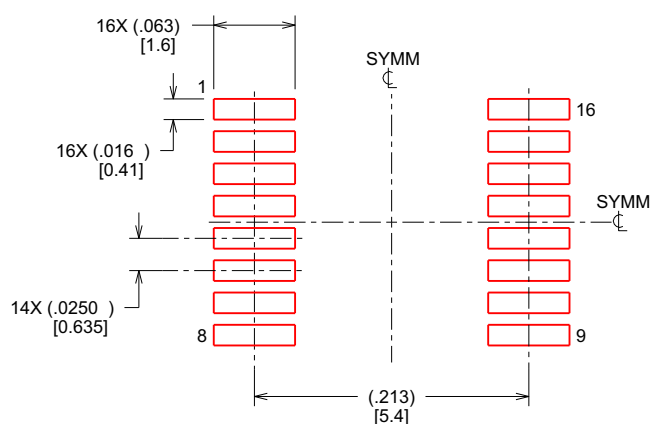
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EXAMPLE STENCIL DESIGN

DBQ0016A

SSOP - 1.75 mm max height

SHRINK SMALL-OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.127 MM] THICK STENCIL
SCALE:8X

4214846/A 03/2014

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPD3S714QDBQRQ1	Active	Production	SSOP (DBQ) 16	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	RJ714Q
TPD3S714QDBQRQ1.A	Active	Production	SSOP (DBQ) 16	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	RJ714Q
TPD3S714QDBQRQ1.B	Active	Production	SSOP (DBQ) 16	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	RJ714Q

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

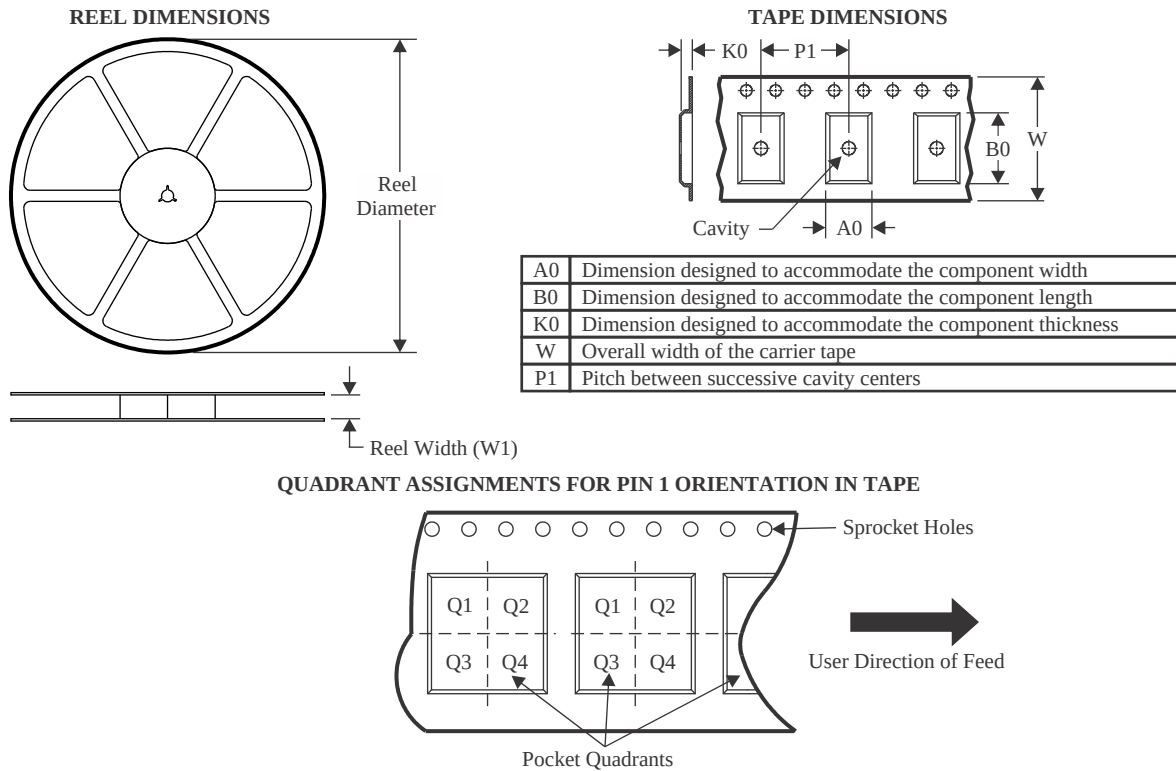
⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

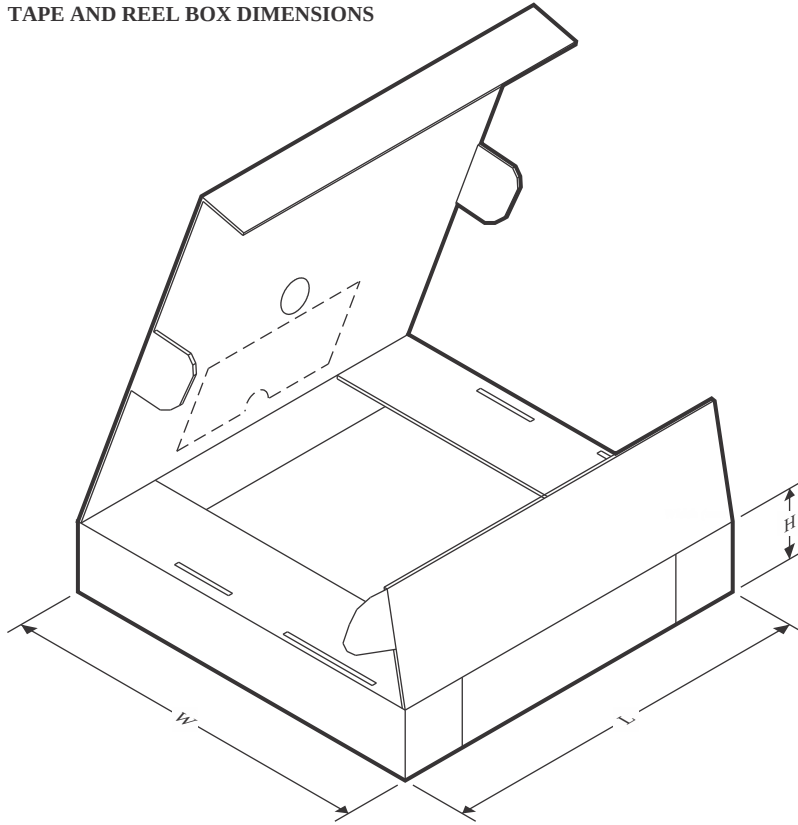
TAPE AND REEL INFORMATION



*All dimensions are nominal

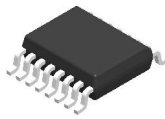
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPD3S714QDBQRQ1	SSOP	DBQ	16	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPD3S714QDBQRQ1	SSOP	DBQ	16	2500	353.0	353.0	32.0

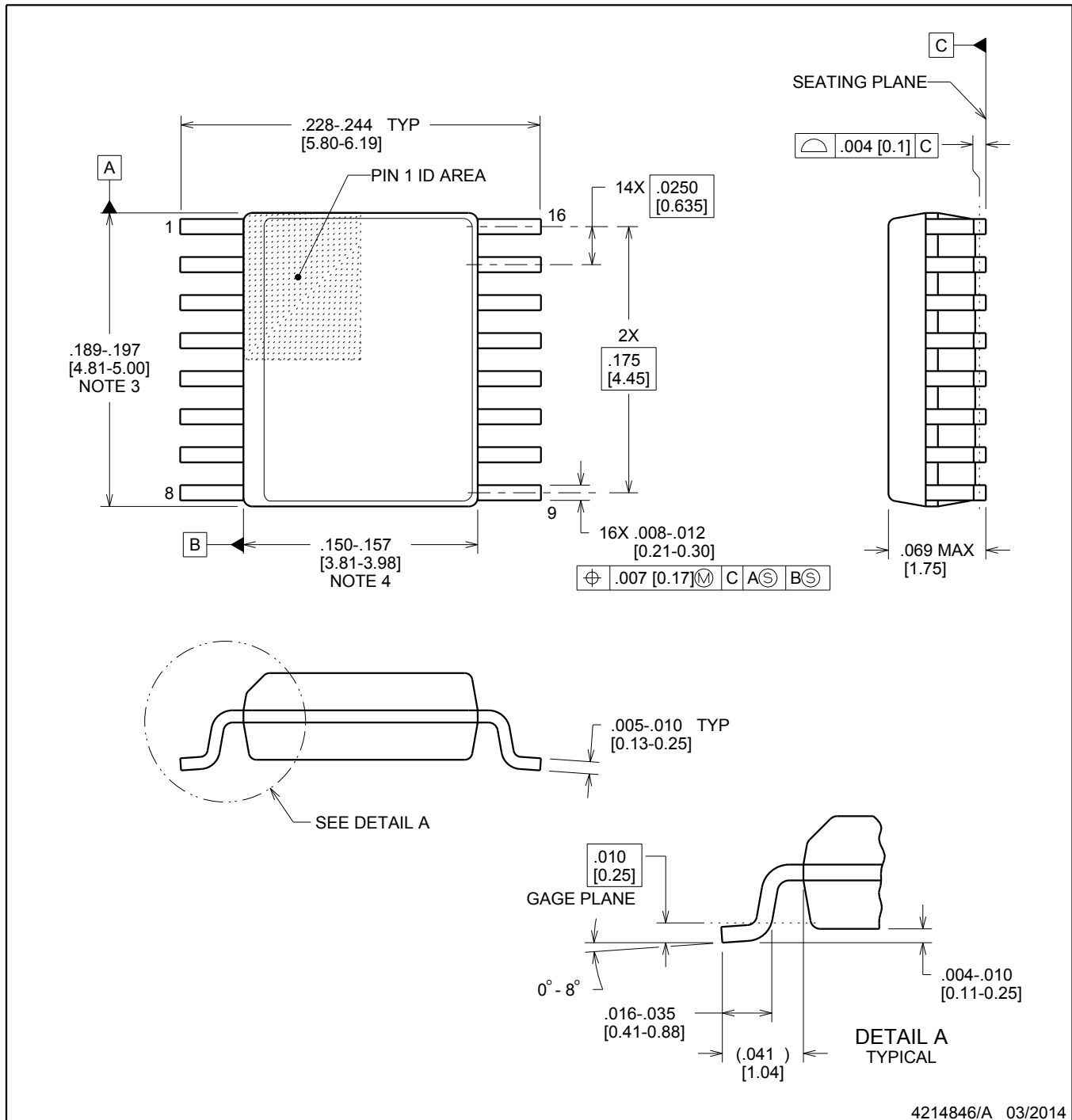


DBQ0016A

PACKAGE OUTLINE

SSOP - 1.75 mm max height

SHRINK SMALL-OUTLINE PACKAGE



4214846/A 03/2014

NOTES:

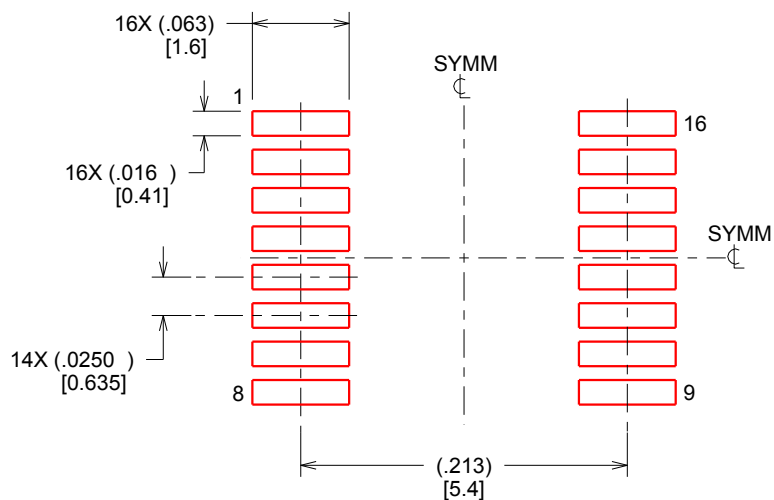
- Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 inch, per side.
- This dimension does not include interlead flash.
- Reference JEDEC registration MO-137, variation AB.

EXAMPLE STENCIL DESIGN

DBQ0016A

SSOP - 1.75 mm max height

SHRINK SMALL-OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.127 MM] THICK STENCIL
SCALE:8X

4214846/A 03/2014

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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最后更新日期：2025 年 10 月